

Electronic Acknowledgement Receipt

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Application Number:	10780932
Confirmation Number:	1914
Title of Invention:	Interconnect structure for TFT-array substrate and method for fabricating the same
First Named Inventor:	Kun-Hong Chen
Customer Number:	24504
Filer:	Daniel R. McClure
Filer Authorized By:	
Attorney Docket Number:	250122-1220
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment After Final	00401270.pdf	105018	no	5

Warnings:**Information:****Total Files Size (in bytes):**

105018

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.